景碩科技股份有限公司

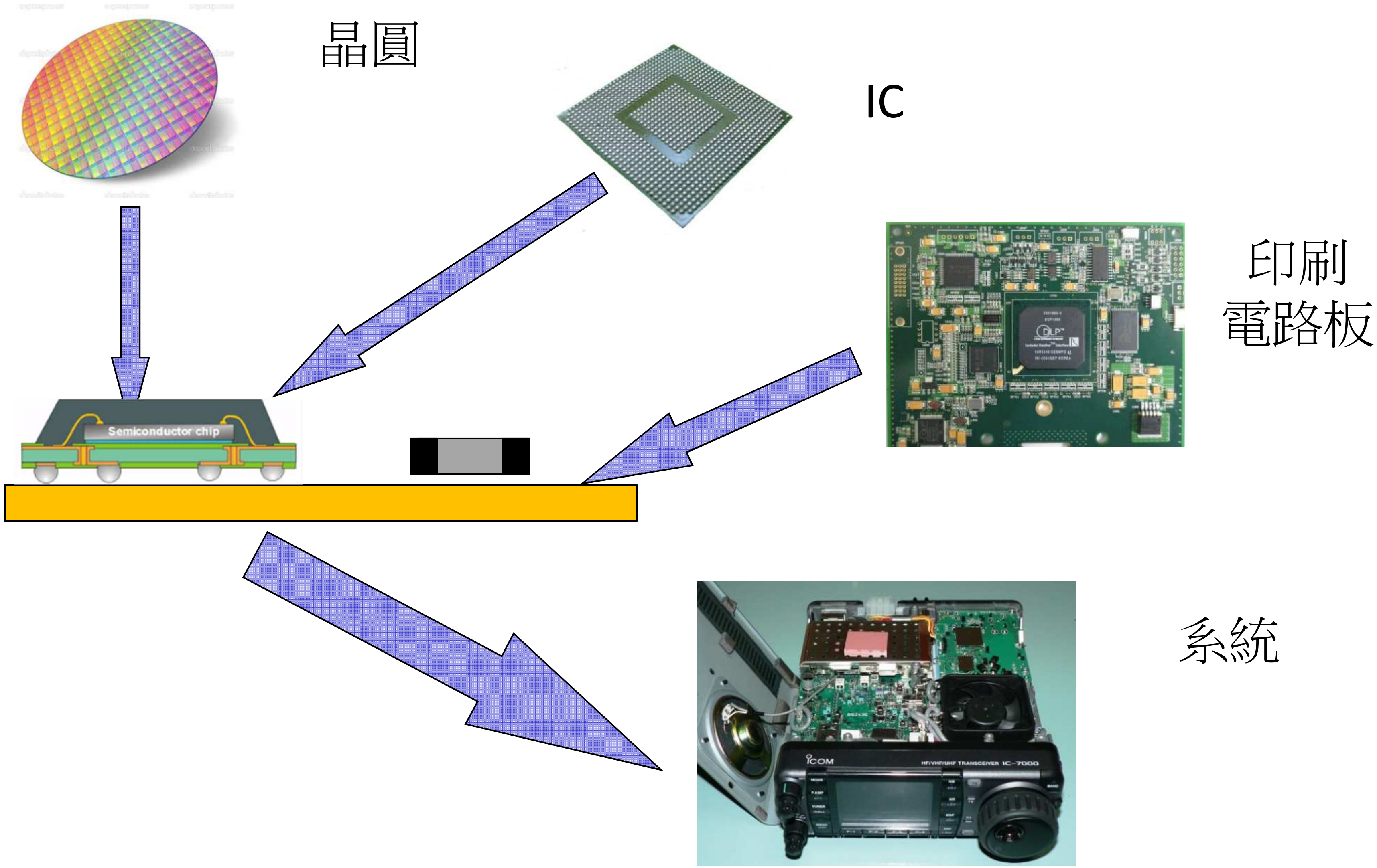
Kinsus Interconnect Technology Co.

Kinsus Tech.

2015 June

IC 封裝技術
IC Packaging Technology

電子產品構裝的各個層次



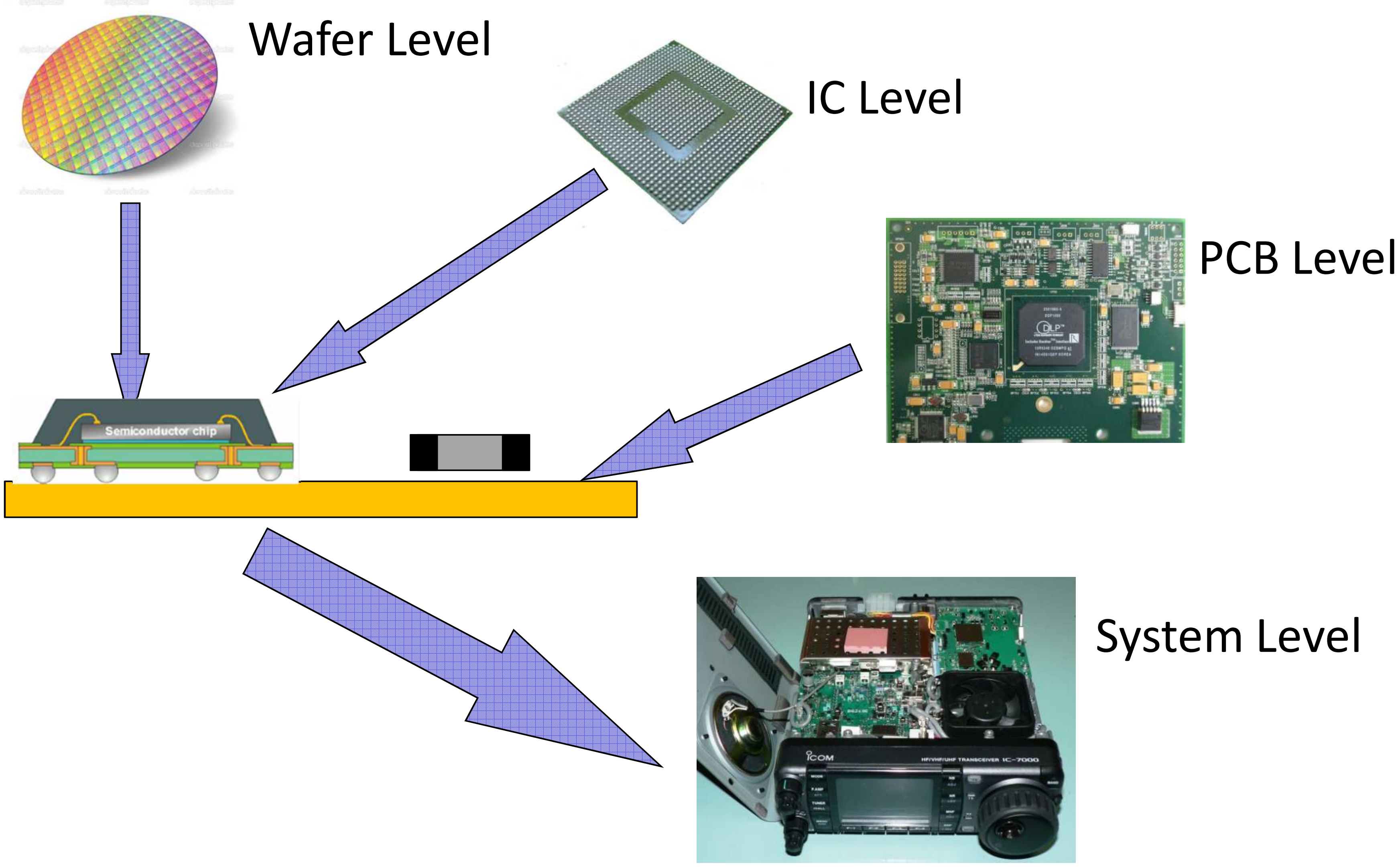
晶圓

IC

印刷
電路板

系統

Levels of Assembly in Electronic Devices



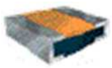
Wafer Level

IC Level

PCB Level

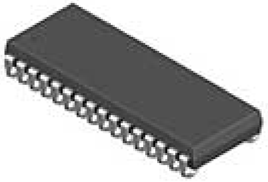
System Level

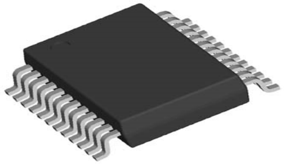
各種形式的 IC 封裝

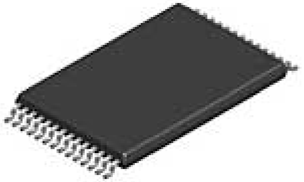

Chips

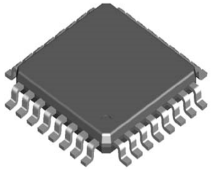

SOT/SOD

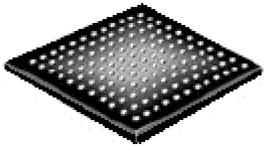

DPAK

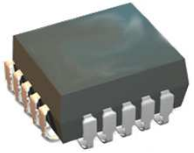

SOJ

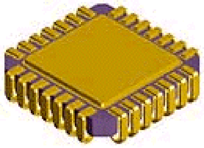

SOIC/SSOP/
OSOP/TSSOP/
MSOP/HSOP


TSOP


OFP/TOFP
/LOFP


BGA/Flip-Chip
/WLP


PLCC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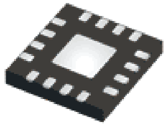
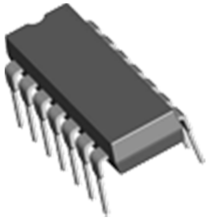

QFN


DFN


DIP

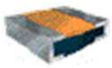

Axial


Radial

Through-hole

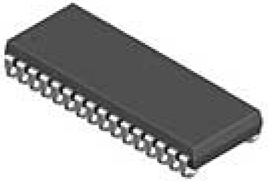
Different types of IC packaging

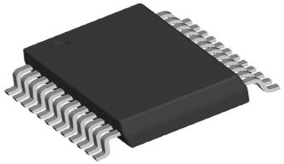
Kinsus Tech.

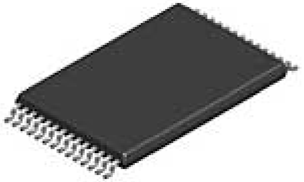

Chips

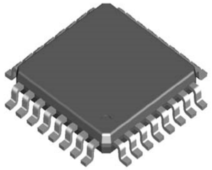

SOT/SOD

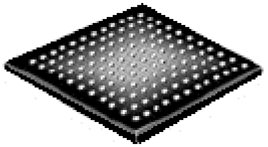

DPAK

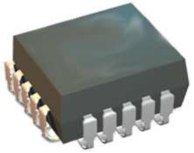

SOJ

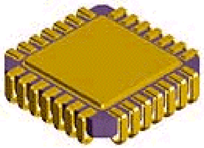

SOIC/SSOP/
OSOP/TSSOP/
MSOP/HSOP

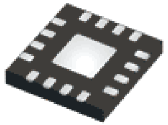

TSOP


OFP/TOFP
/LOFP

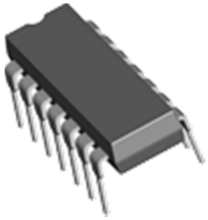

BGA/Flip-Chip
/WLP


PLCC


CLCC


QFN


DFN

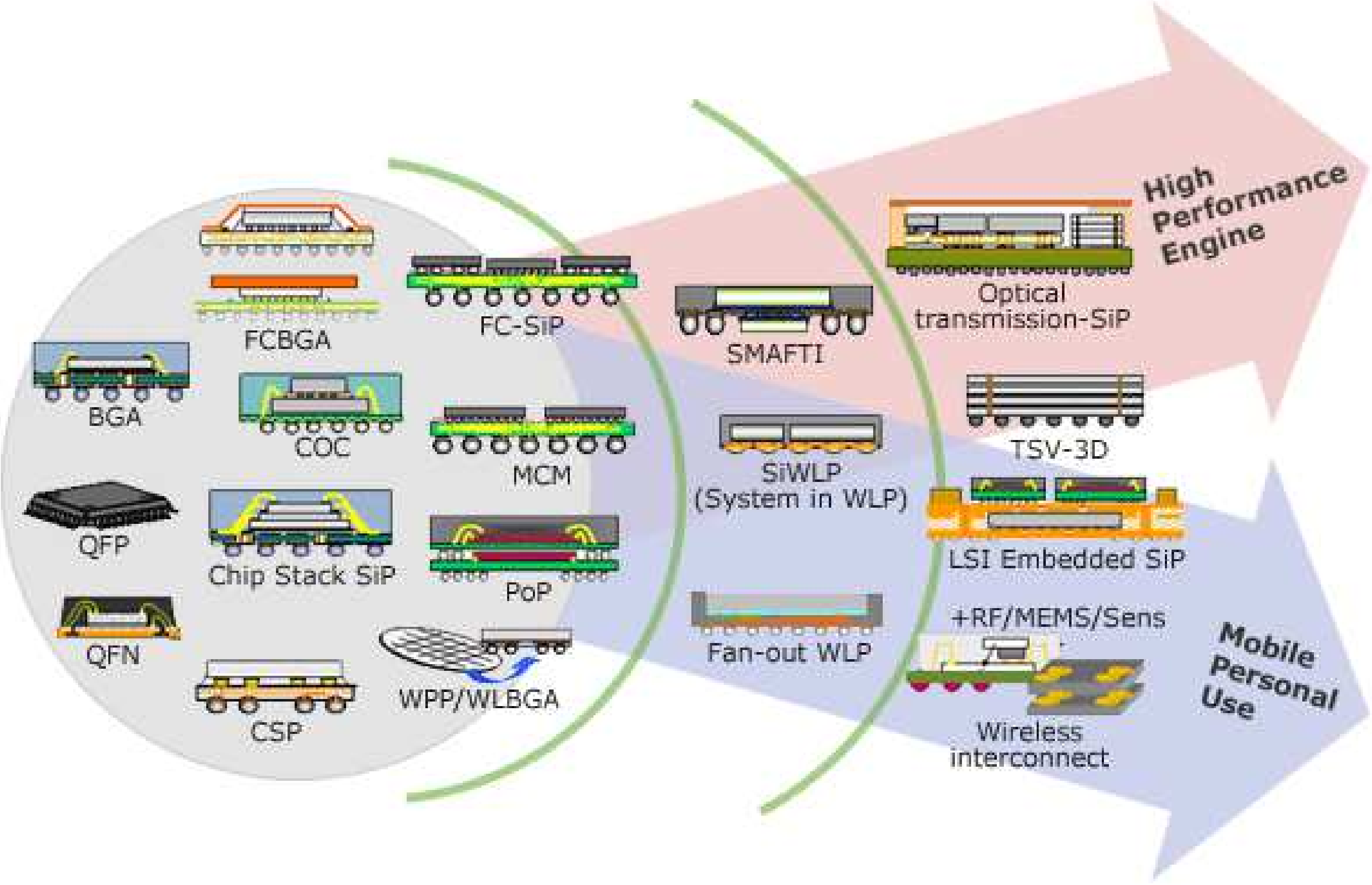

DIP


Axial

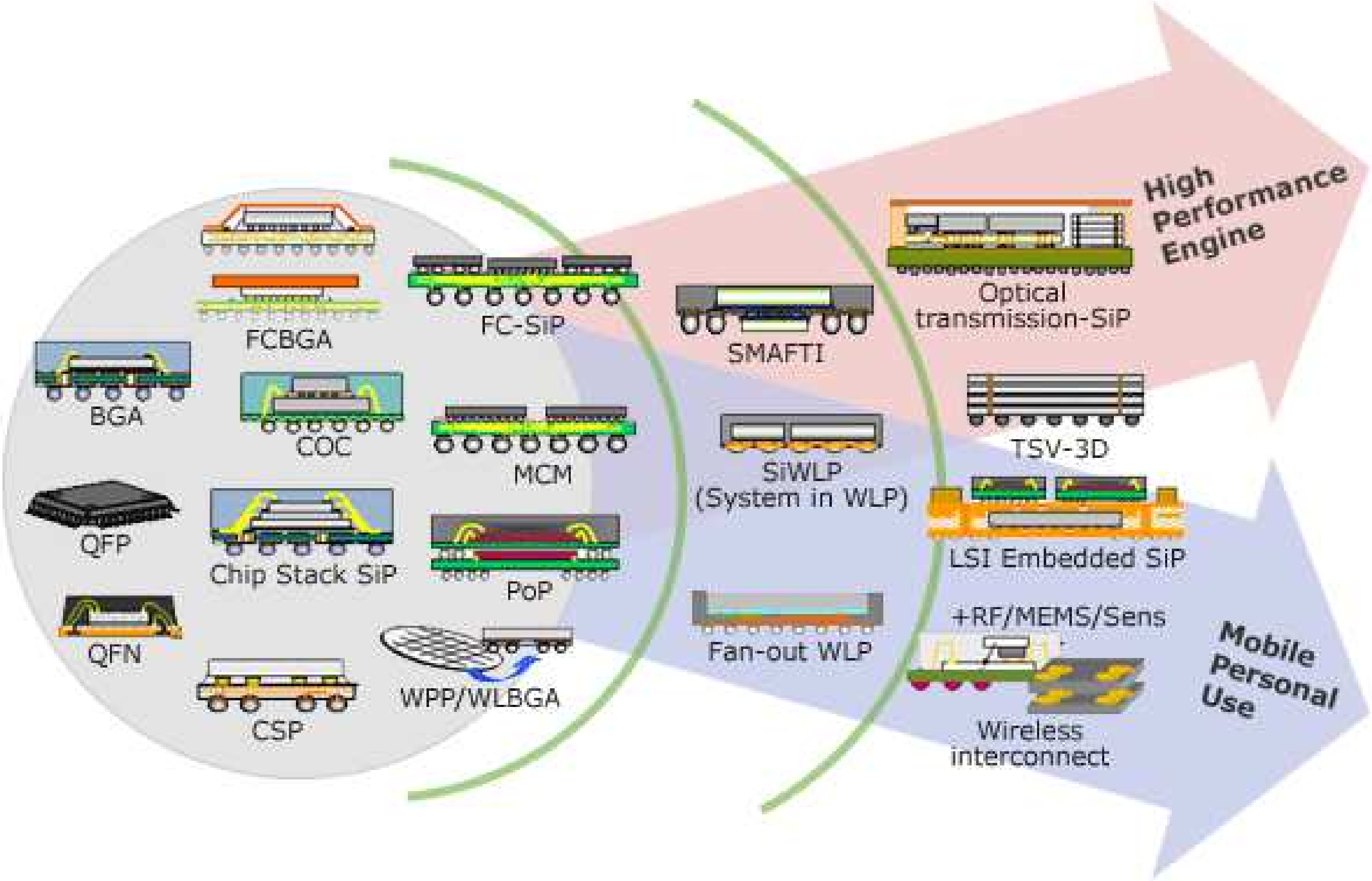

Radial

Through-hole

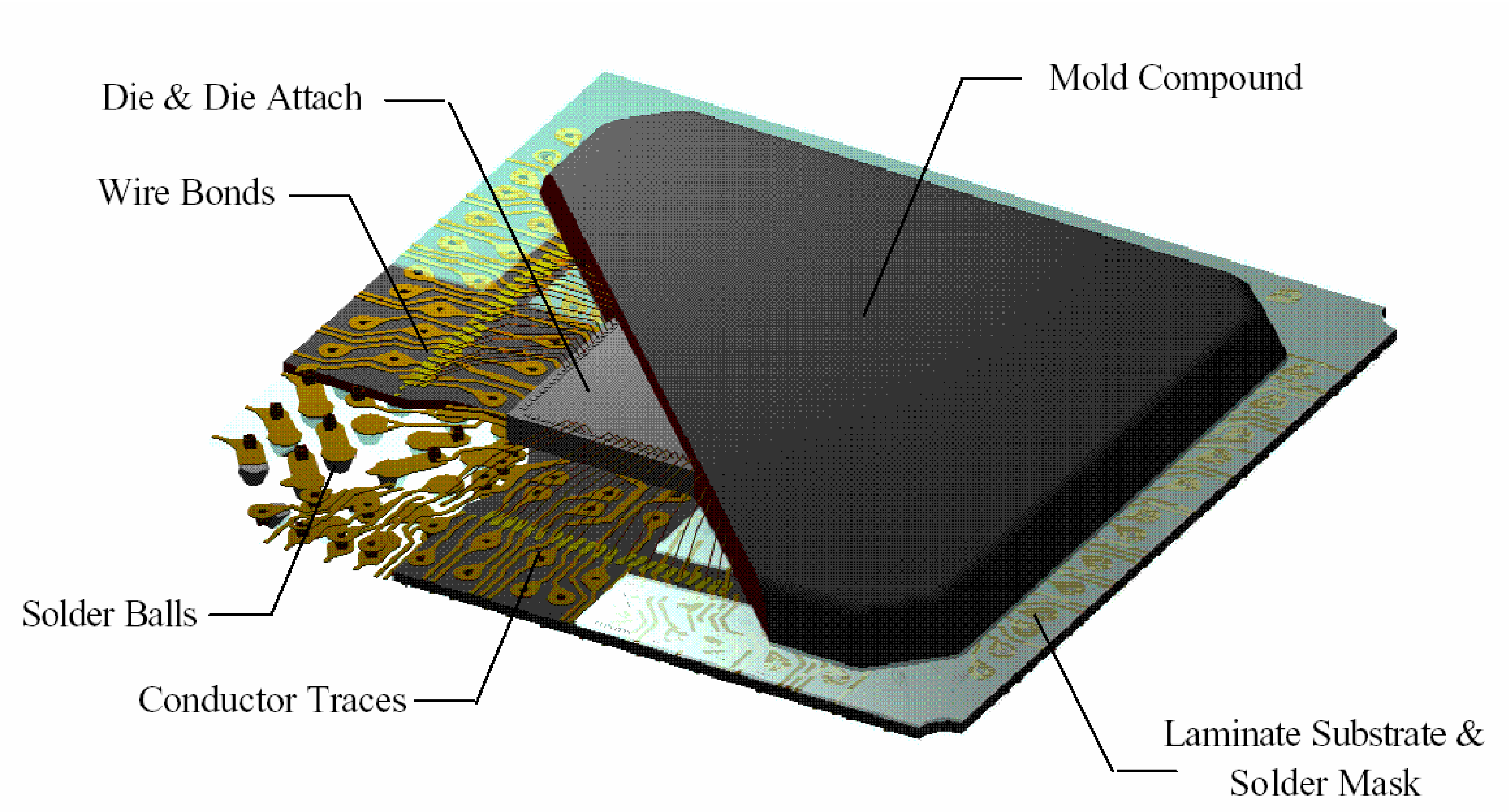
封裝技術走向


FCBGA
FC-SiP
BGA
COC
MCM
QFP
Chip Stack SiP
PoP
QFN
CSP
WPP/WLBGA
SMAFTI
SiWLP
(System in WLP)
Fan-out WLP
Optical
transmission-SiP
TSV-3D
LSI Embedded SiP
+RF/MEMS/Sens
Wireless
interconnect
High
Performance
Engine
Mobile
Personal
Use

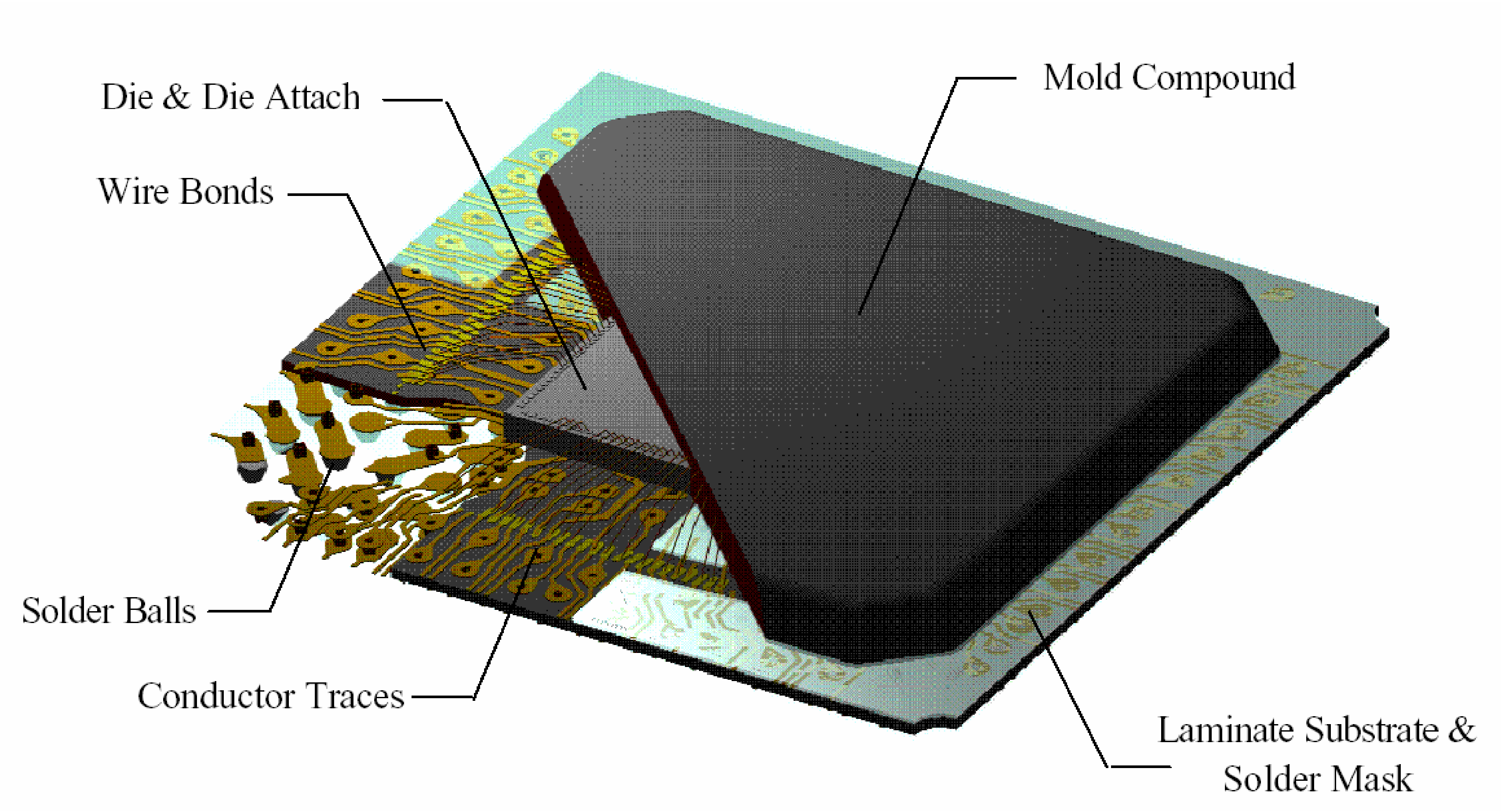
Packaging Technology Roadmap



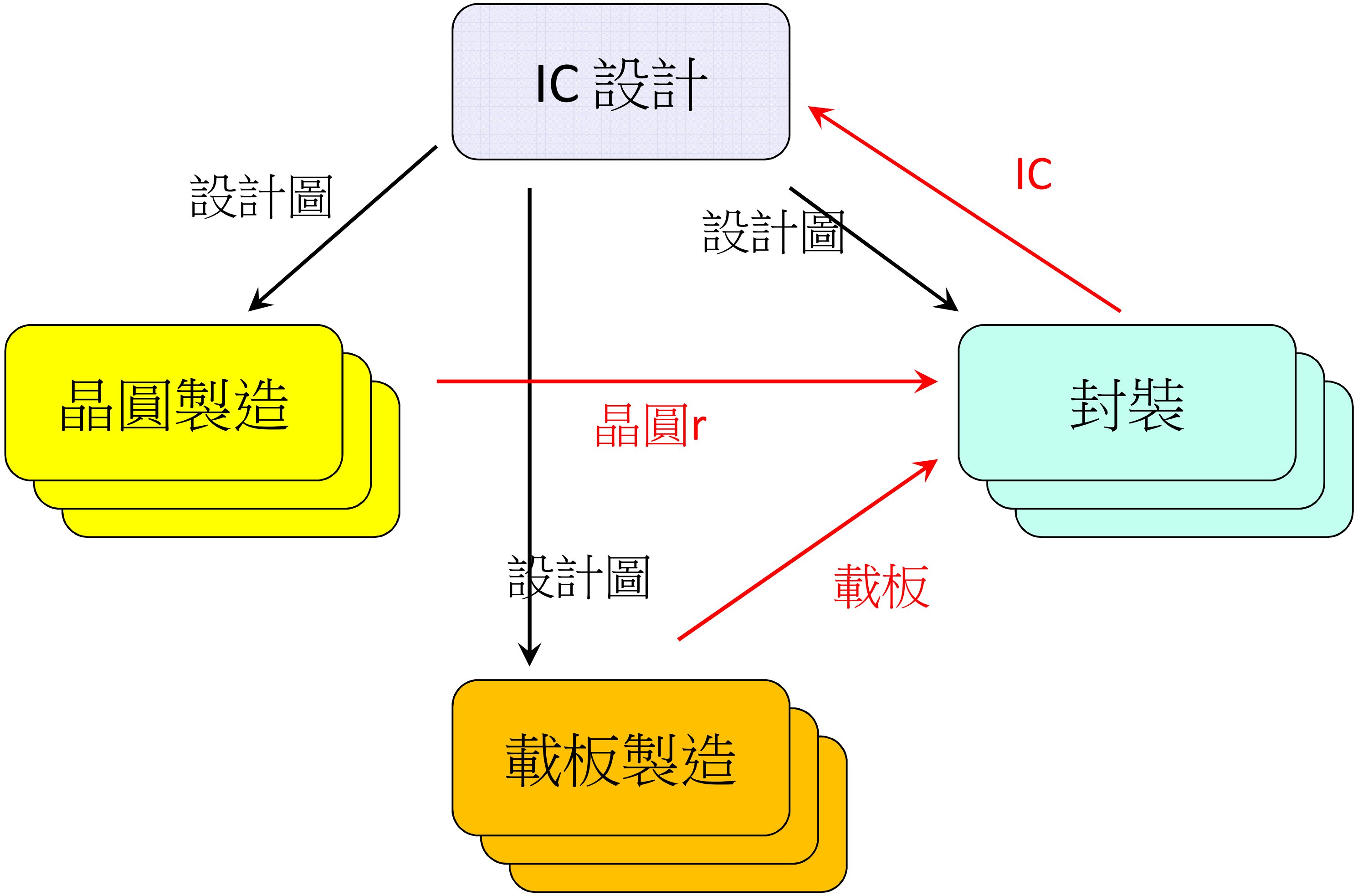
IC 結構


Die & Die Attach
Wire Bonds
Mold Compound
Solder Balls
Conductor Traces
Laminate Substrate &
Solder Mask

What Substrate Makers do?



IC 半導體上下游供應鏈關係



IC 設計

設計圖

設計圖

IC

晶圓製造

封裝

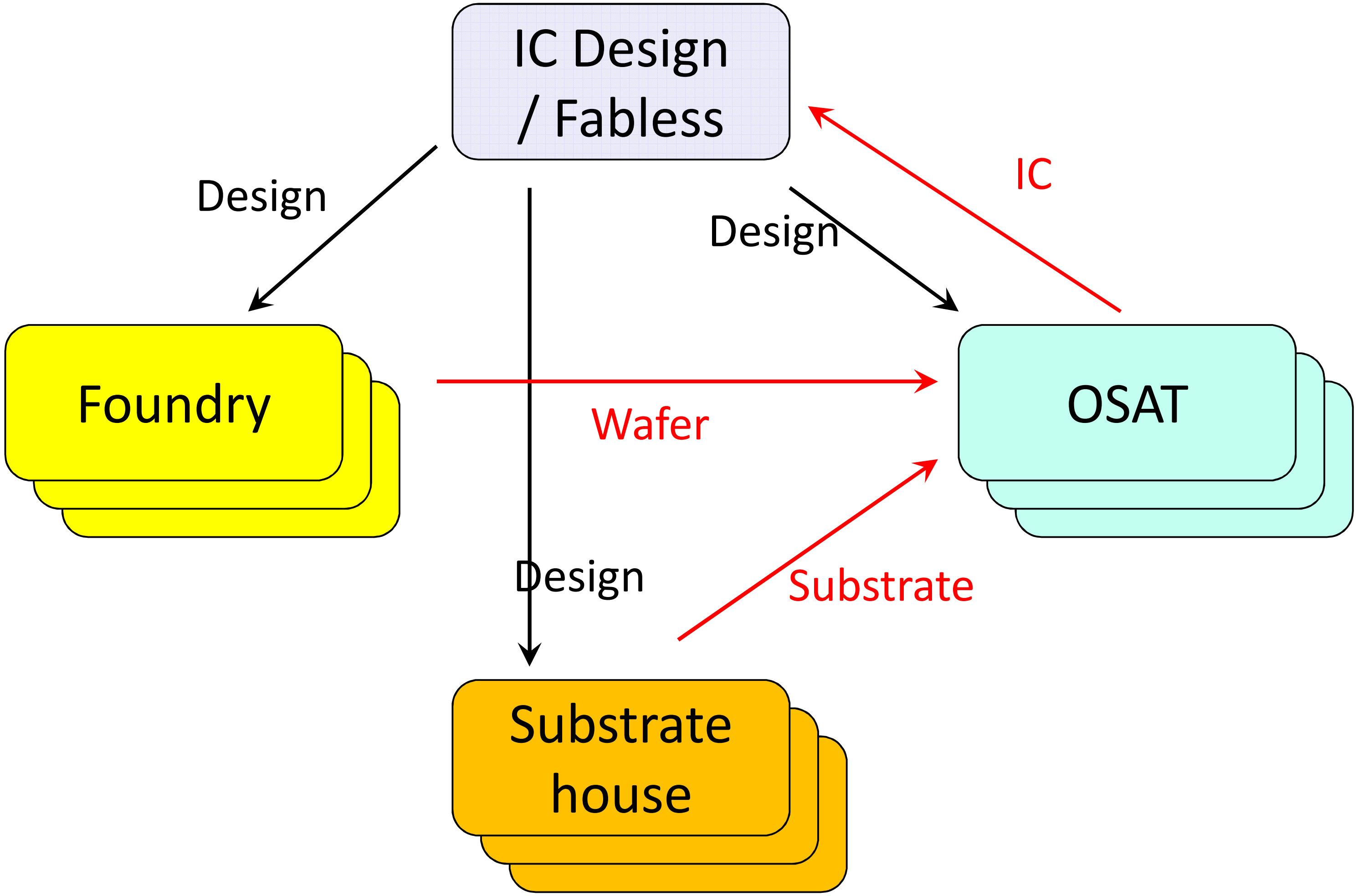
晶圓r

設計圖

載板

載板製造

IC Manufacturing Supply Chain


IC Design / Fabless

Foundry

OSAT

Substrate house

Design

Design

Design

IC

Wafer

Substrate

About Kinsus

基本資料

- 成立September 2000
  上市 November 2004
- 登記資本額 新台幣 44.6 億
- 員工數 : 3,600 (2015 四月)
- 廠區 :
  總部 - 石磊 / 新屋鄉
  硬質載板事業部 - 一廠, 二廠
  - 四廠
  軟質載板事業部 - 四廠
  美國子公司 - Santa Clara / California
  中國子公司 - 蘇州

Basic Information

- Established in September 2000

  IPO in November 2004

- Capital : US$ 154 Million (NT$ 4.46 Billion)

- Headcounts : 3,600 as of April 2015

- Campus :
  - Headquarters - Shih Lei / Sin Wu
  - Rigid Substrates BU - Plant I, Plant II
    - Plant VI
  - Flexible Substrate BU - Plant VI
  - Kinsus USA - Santa Clara / California
  - Kinsus China - Suzhou

位置

Kinsus Suzhou（統碩）

Piotek（百碩）

美國子公司

一廠

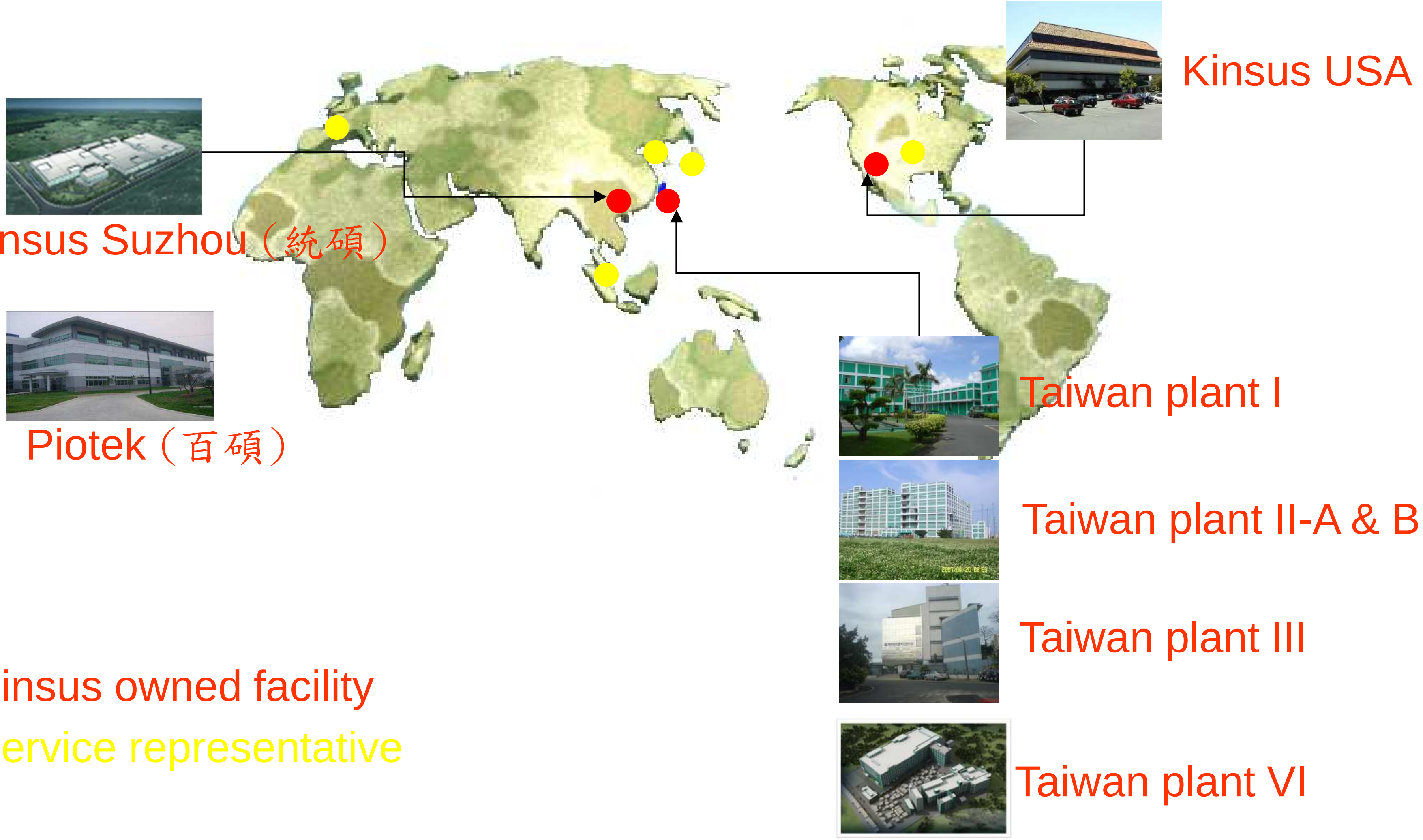
二廠 A&B

三廠

四廠

- ● 景碩自有廠房辦公室
- ● 業務代表/代理

Locations



Kinsus USA

Kinsus Suzhou（統碩）

Piotek（百碩）

Taiwan plant I

Taiwan plant II-A & B

Taiwan plant III

Taiwan plant VI

- 🔴 Kinsus owned facility
- 🟡 Service representative

硬質載板產品

Desk Top,
PCMCIA cards,
notebook,
video cameras

Server, Switch,
Set-Top Box,
Home Game,
CPU / BUS boards

Digital camera,
Cellular,
wireless,
MP3 Player,
DROM

Rigid Substrate Products

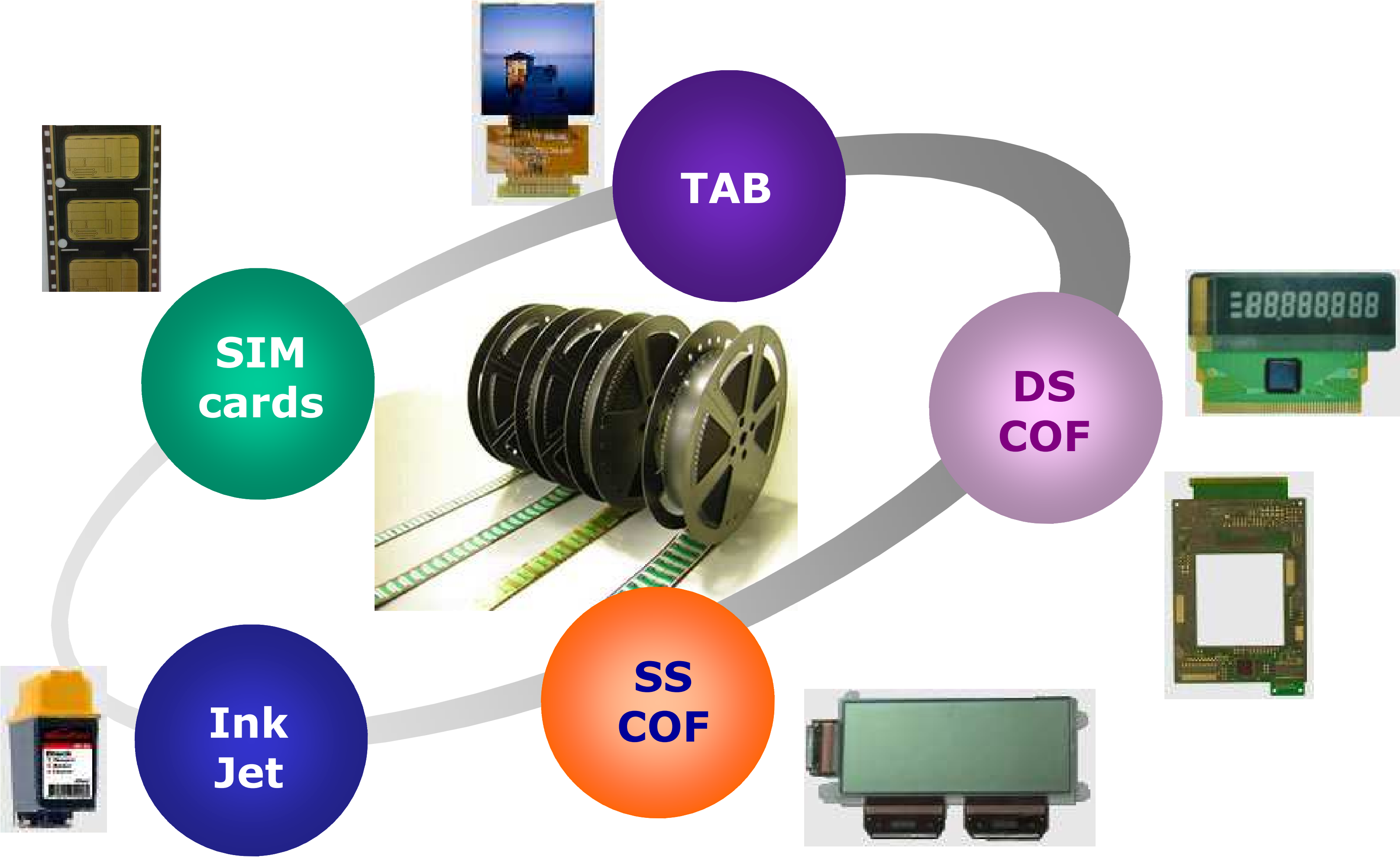
Desk Top,
PCMCIA cards,
notebook,
video cameras

Server, Switch,
Set-Top Box,
Home Game,
CPU / BUS boards

Conventional
EBGA
Fine Pitch
PBGA
Cavity Down
Laser EBGA
FC CSP
Thin CSP
Flip Chip
CSP
FC High IOs
Chip Array
MCM
Module
RF Module
COB
SIP

Digital camera,
Cellular,
wireless,
MP3 Player,
DROM

軟質載板產品



TAB

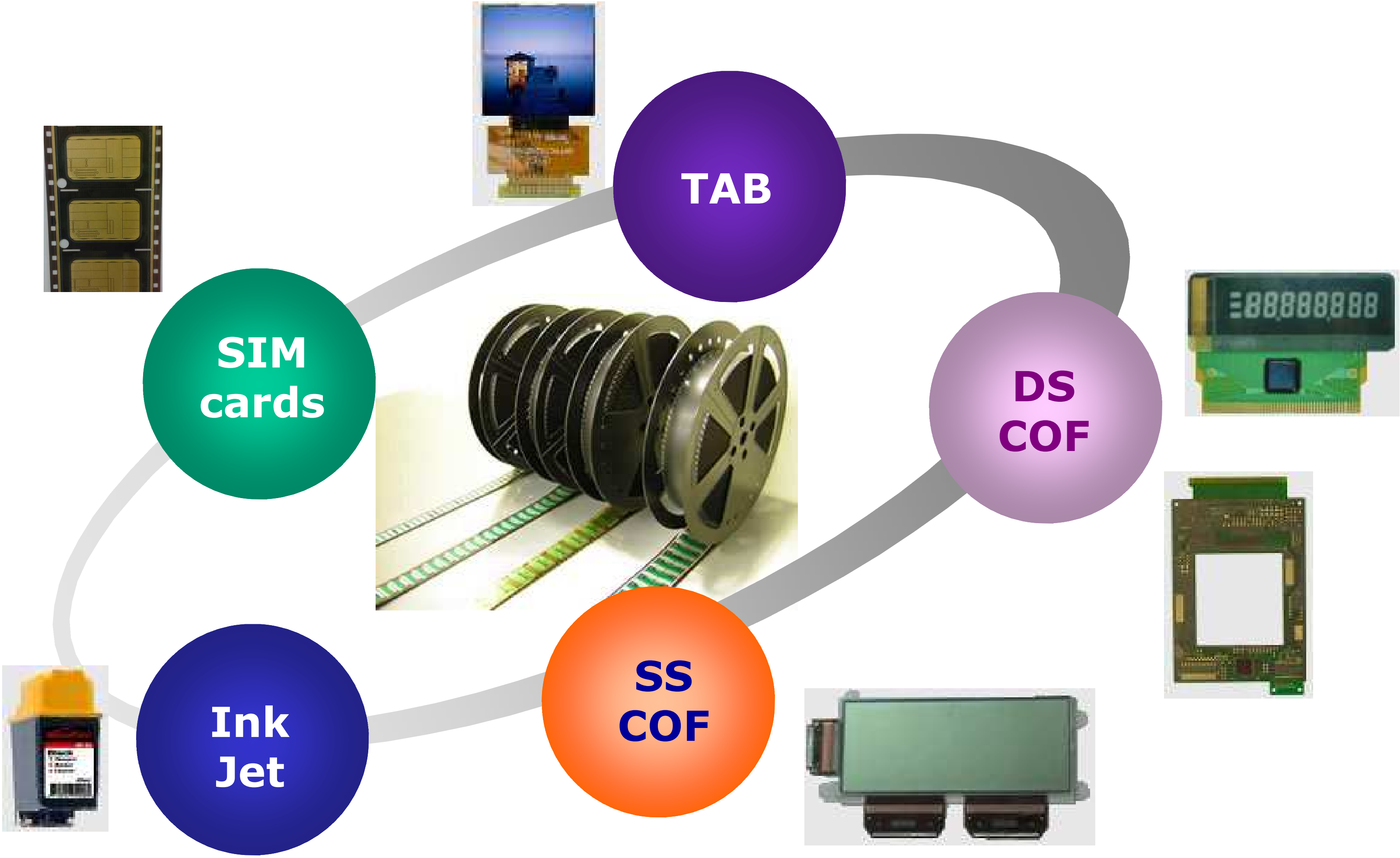
SIM cards

DS COF

SS COF

Ink Jet

Flexible Substrate Products



TAB

SIM cards

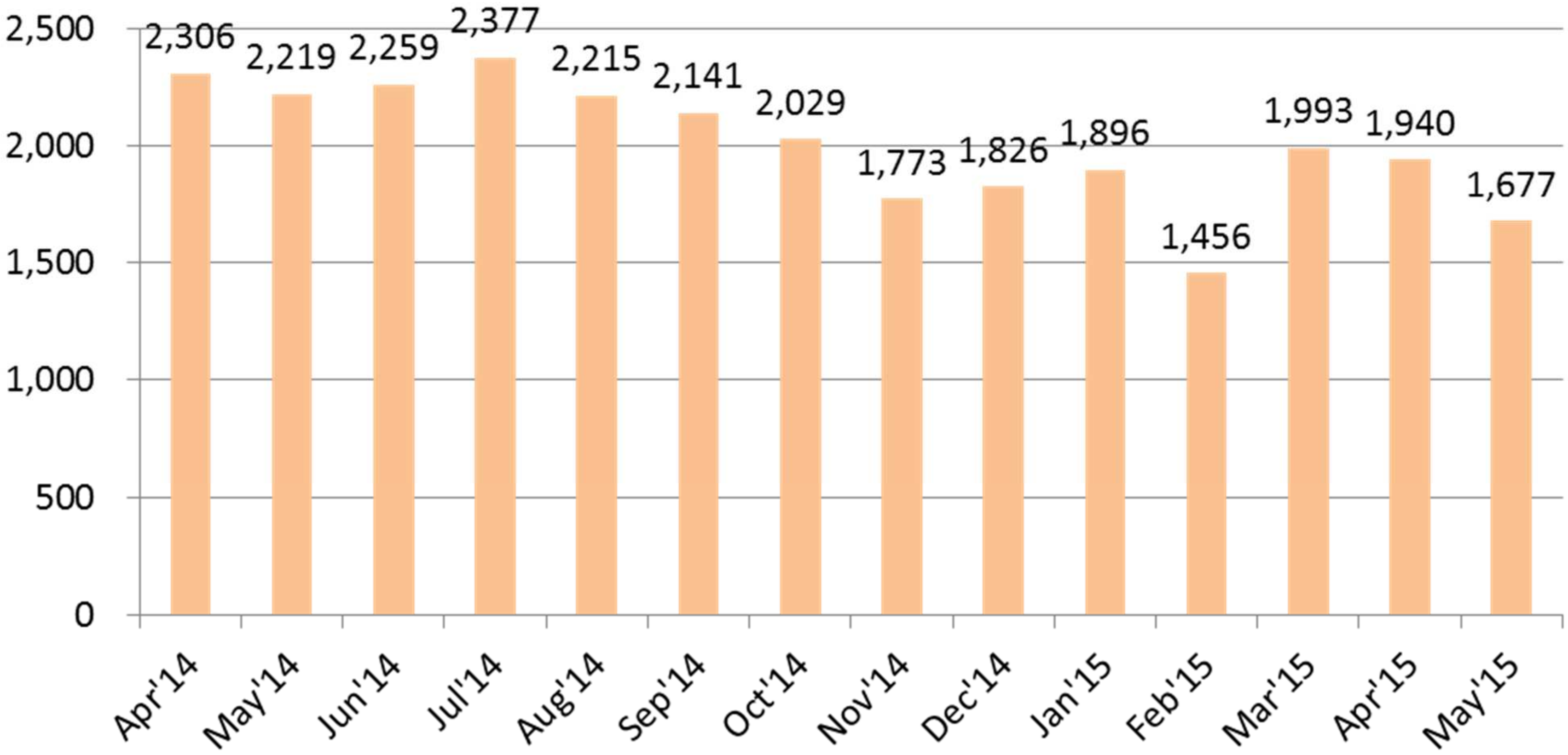
DS COF

Ink Jet

SS COF

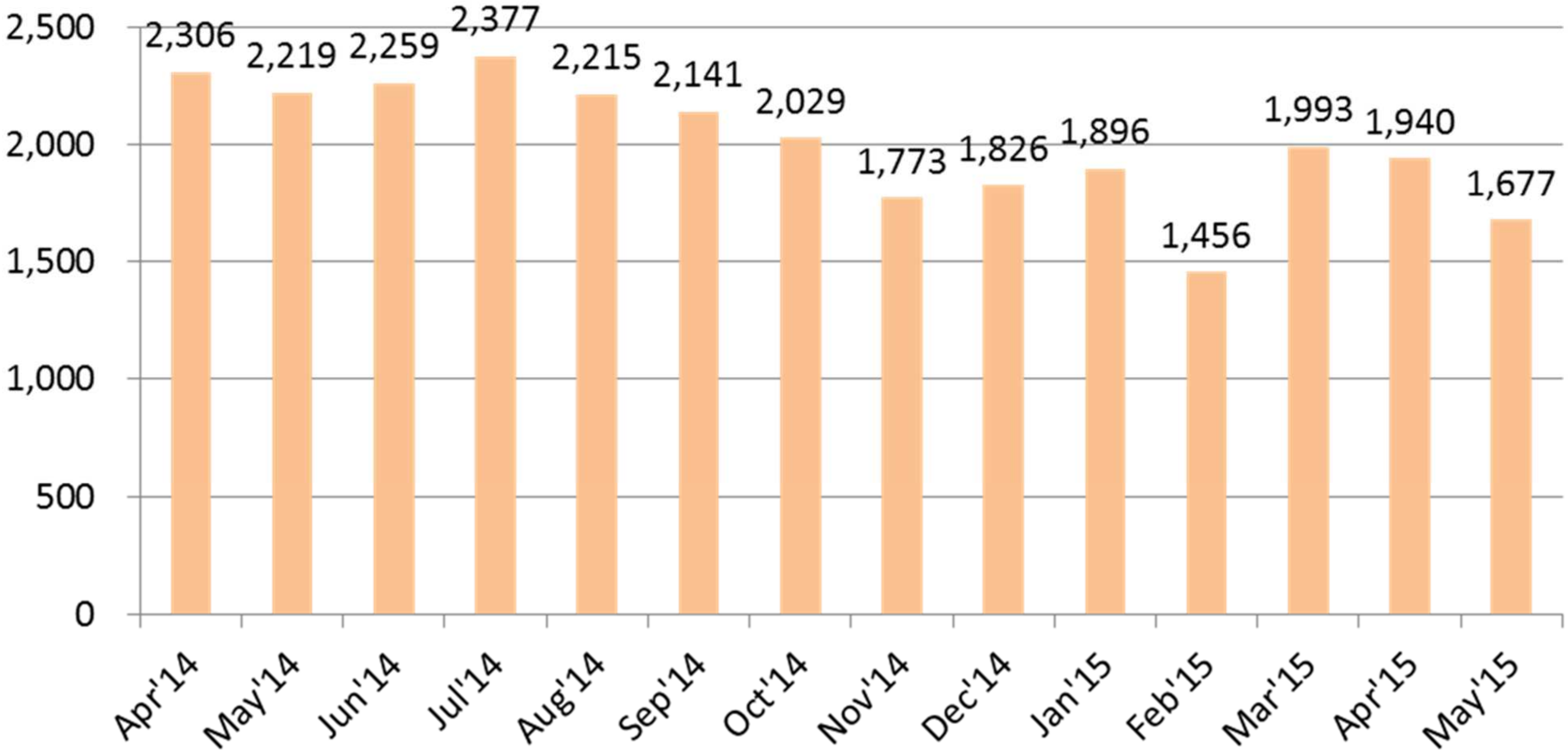
每月營業額

單位 ： 新台幣百萬元

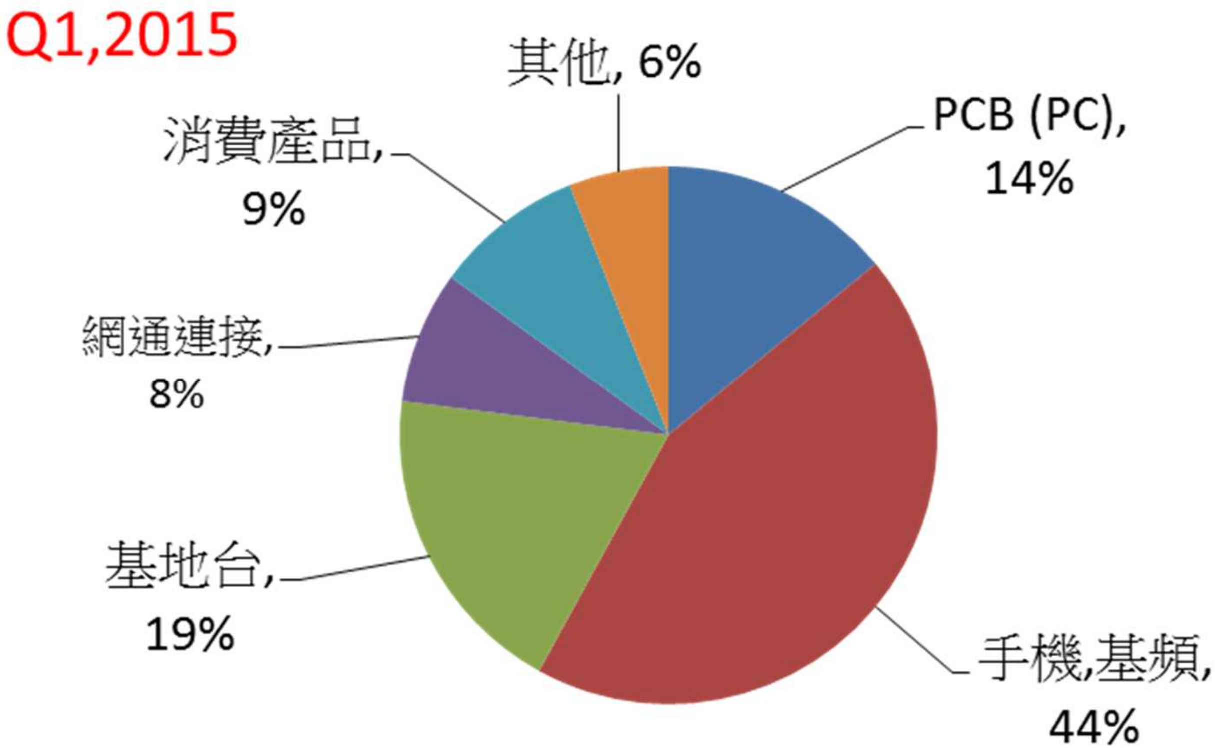


Monthly Revenue

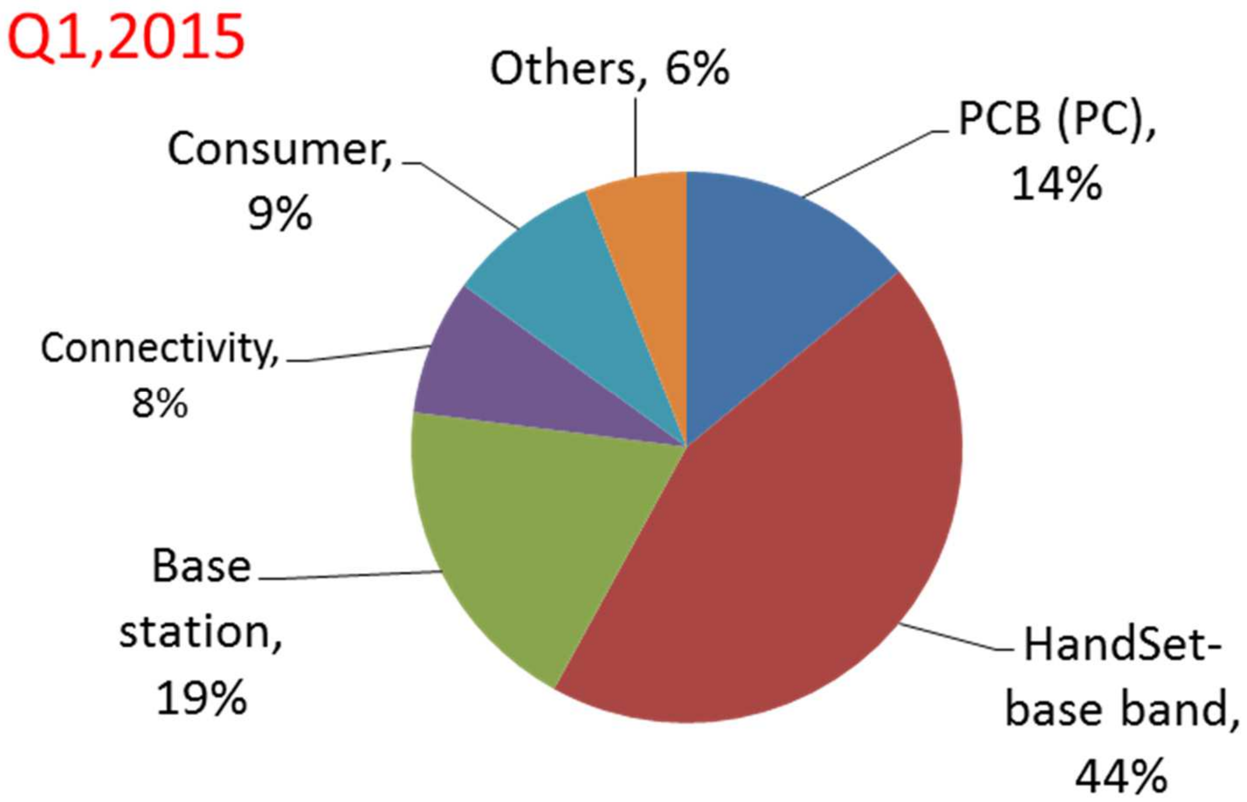
Unit : Million NT$



營業額分佈



Revenue - Application



Thank You!